

**Preliminary Amendment**

Applicant: Min Wee Low, et al.

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Title: **NON-LEADED SEMICONDUCTOR PACKAGE AND A METHOD TO ASSEMBLE THE SAME**

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**IN THE ABSTRACT**

Please replace the Abstract with the following rewritten paragraph:

**NON-LEADED SEMICONDUCTOR PACKAGE AND A METHOD TO ASSEMBLE  
THE SAME****Abstract**

A method to assemble a non-leded semiconductor package (1) comprises the following steps is disclosed. In one embodiment, A carrier tape (13) is attached to a metal foil (12). A plurality of leadframes (3) is are formed in the metal foil (12), each leadframe (3) comprising including a die pad (4) laterally surrounded by a plurality of contact leads (5). A semiconductor die (2), including an active surface with a plurality of die contact pads (7), is attached to each die attach pad (4) and electrically connected to the leadframe (3) by a plurality of bond wires (9) connecting the die contact pads (7) and the lead contact areas (6) of the contact leads (5). A plurality of leadframes (3), each including a wire bonded semiconductor die, are encapsulated with mold material (10). The carrier tape (13) is removed and the non-leded semiconductor packages (1) separated.

{Fig-5}